ELECTRONICS CO., LTD,

SPECIFICATION

TITLE SPC. NO. PAGE: 1 OF 7
MINIATURE JACK 3.5 Miniature Jack series-DIP DATE: 2013.09.02

SPECIFICATION

1. Standard atmospheric condition

Unless otherwise specified, the standard range of atmospheric conditions for making

measurements and tests are as follows:

Ambient temperature: 15°C to 35°C

Relative humidity : 25% to 80%

Air pressure : 86kPa to 106kPa

If there is any doubt about the results, measurements shall be made within the following limits:

Ambient temperature: $20 \pm 2^{\circ}$ C Relative humidity : 60% to 70%

Air pressure : 86kPa to 106kPa

Operating temperature range: -25° C to 65° C Storage temperature range: -25° C to 85° C

2. Electrical characteristics:

	Item	Cone	Specifications	
1	Rated voltage Rated current		DC 12V 1A	
2	Contact resistance	Measurement shall be made at v (1A MAX.)	30mΩ MAX.	
3	Insulation resistance	A voltage of 500V DC shall be applied for 1 minute after which measurement shall be made.	Between the conductors which should not make contact under normal conditions. Between each terminal and insulated metal part.	100MΩ MIN.

ISSUE	DATE	WRTN	CHKD	APVD	DESCRIPTIONS
	2013.09.02	江浩霆	郭素玲	郭遠峰	To revise the Specification from HTJ-035series-DIP(F)

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	Item	Cond	Specifications	
4	LDielectric	500V AC (50 Hz to 60 Hz) for 1 minute. Trip current : 2mA	normal conditions.	Without damage to parts, arcing or breakdown, etc.

3. Mechanical characteristics

	Item	Cond	dition	Specifications
1	Operating	Insertion and withdrawal for after inserting and withdraw gauge of standard dimension		
	force	Insertic	$4N\sim30N (0.4kgf\sim3.0kgf)$	
		Withdra	$3N\sim30N (0.3kgf\sim3.0kgf)$	
2	Contact pressure	Contact pressure during the make contact shall be measured in the operation by using the minimum dimensional gauge. The contact pressure during measured under the normal	The contact pressure between chip, ring, sleeve and the contact piece. The contact pressure with the make contact. g the break contact shall be conditions.	1N (100gf) MIN.

4. Endurance characteristics

	Item	Condition	Specifications	
		Temperature : 40°C±5°C	Dimensional requirements shall	
		Relative humidity: 90% \sim 95% for 96 hours after	be satisfied.	
		testing jack shall be left alone for 1 to 2 hours in a	Electrical and mechanical	
	Humidity	room ambient.	characteristics shall be satisfied.	
		Contact resistance	50 m Ω MAX.	
	test	Insulation resistance	50MΩ MIN.	
		Contact pressure	0.5N (50gf) MIN.	
		Insertion force	3N~30N (0.3kgf~3.0kgf)	
		Withdrawal force	311,~3011 (0.3kg1,~3.0kg1)	

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	MINIATURE JACK		3.5	Miniature Jack	series-I	OIP	DATE : 2013.09.02		
	Item		Con	dition		Specifications			
2	Cold	The jack shall be stored for 96 hours at a temperature of $-25\pm2^{\circ}$ C immediately after which measurement shall be made			Dimensional requirements shall be satisfied. Electrical and mechanical characteristics shall be satisfied.				
				on force		3N	\sim 30N (0.3kgf \sim 3.0kgf)		
3	Dry heat	<u> </u>	ored for 96 hours at a 2°C immediately after which			Dimensional requirements shall be satisfied. Electrical and mechanical characteristics shall be satisfied.			
			Insertion force Tithdrawal force			$3N\sim30N (0.3kgf\sim3.0kgf)$			
4	Operating	Jack shall withstand 5000 cycles inserting and withdrawing shall be made by the following mating plug or standard dimension gauge, at a speed of 10				Dimensional requirements shall be satisfied. Electrical and mechanical characteristics shall be satisfied.			
4	endurance	to 30 times / min.	ontact	t pressure		Chara	0.5N (50gf) MIN.		
		Contact resistan		Each closed co			60m Ω MAX. 100m Ω MAX.		
5	Soldering test	Time of dip: 3±0.5	Between plug and contact Temperature of solder: 250°C±5°C Time of dip: 3±0.5 seconds Length of dip: 2±0.5mm (from top of terminal)				The soldered area shall be covered a minimum of 90% of the surface being immersed.		
	Sleeve	As shown the below plug to our jack, you Then you use the 2K with 4 directions (u) Note: P=19.8N (2)	ı must Eg stre ıp, do	t put it in fixed local ength into its front s wn, left, right).	ation.		sleeve should not be loosen the test for 1000 circles.		
6	strength (for sleeve items only)	P		FIX	P	L	FIX		

FIX HOUSING

Mating plug

FIX HOUSING

Mating plug

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	Item		Condition		Specifications		
		Wave soldering Process					
		Profile Feature	Pb-Free A	Assembly Padside PCB			
		Preheat -Temperature min -Temperature max -Time (t _s min to max)	120°C (T _{sl} max)	$ \begin{array}{c} 110^{\circ}\mathbb{C} \\ (T_{s} \min) \\ 150^{\circ}\mathbb{C} \\ (T_{s} \max) \\ 75 \text{ sec} \end{array} $	Electrical and mechanical characteristics shall be satisfied,		
		Peak/Classification Temperature Time within 5°C of actual Temperature	165°C (T _{pl} max)	260°C ±5°C (T _p) 10 sec (within 2 times every	and not show remarkable failure.		
		(t_p) Time 25°C to Peak temperature		time 2-3 sec) 3 minutes max			
	Resistance to	Wave Soldering Temperature Profile are as below About the plastic properties, Please refer to the data sheet of plastic.					
7	Soldering Heat Test	Tp			2~3 sec Tp1 max.		
		Ts min.		ts Topside			
		Soldering Iron Test Temperature of solderi Soldering time: 3±1 so	-	Same as Wave soldering Process			
			ertion force		4N~30N (0.4kgf~3.0kgf)		
		With	ndrawal force		3N~30N (0.3kgf~3.0kgf)		

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	Item	Condition Specifications
8	Composite temperature/ humidity cyclic test	The jack shall be subjected to 10 continuous cycles, each as shown in figure below. Then the jack shall be stored at standard atmospheric conditions for 24 hours for recovery, after which measurement shall be made. *Temperature shall be reduced from 25°C to — 10°C within 30 min. *Humidity uncontrolled at a temperature less than 25°C **Temperature shall be reduced from 25°C to — 10°C within 30 min. *Humidity uncontrolled at a temperature less than 25°C **Temperature shall be reduced from 25°C to — 10°C within 30 min. **Humidity uncontrolled at a temperature less than 25°C
		Time in hours (h)

5. Warning:

Miniature jack shall be dipped, warning to inferior contact by flux and transform mold.

Resistance to flux : It shall be prevention between PCB and housing.

Transform mold : It must not add direct heat to miniature jack.

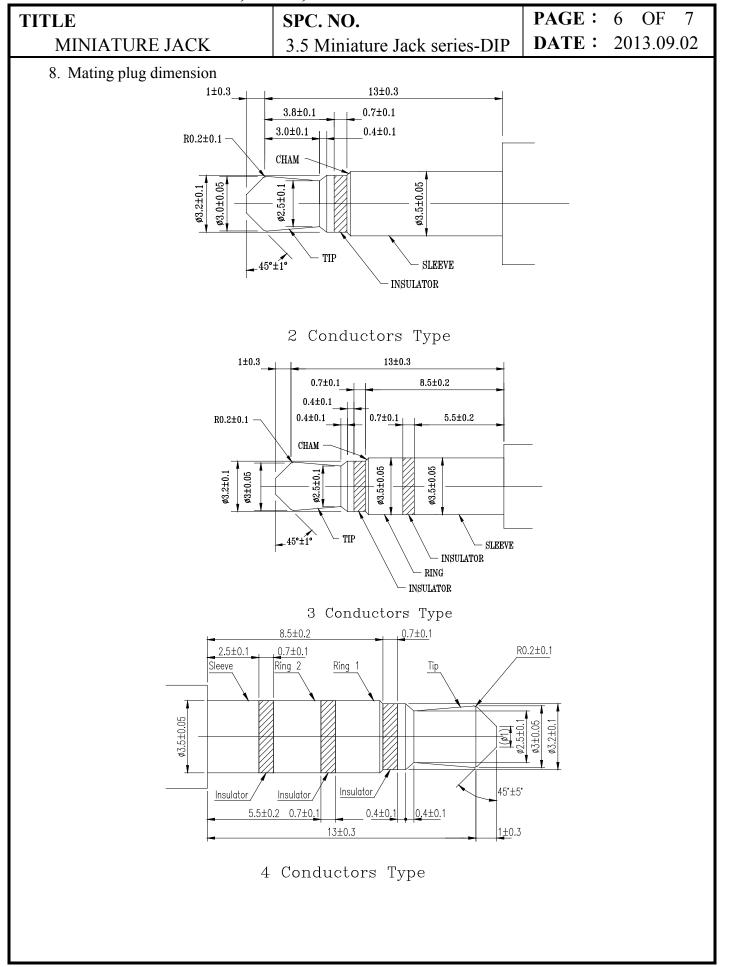
Temperature of solder : 265° C MAX. Preheat temperature : 90° C MAX.

6. Preheat time : 1 minute MAX.

7. Soldering condition shelf life about 6 months depend on storage condition of humidity, temperature and others factors.

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9. Endurance test sequence:

9. Endurance test sequence :										
Test group Test sequence			В	С	D	E	F	G	Н	I
Test Item										
2.2	Contact resistance		1	1,6	1,6	1	1,6		1,6	1,6
2.3	Insulation resistance		2	2,7	2,7	2,7	2,7		2,7	2,7
2.4	Dielectric strength		3,7	3,8	3,8	3,8	3,8		3,8	3,8
3.1	Operating force		4	4	4	4,9	4,9		4	4,9
3.2	Contact pressure	1	5			5				
4.1	Humidity test		6							
4.2	Cold			5						
4.3	Dry heat				5					
4.4	Operating endurance					6				
4.5	Soldering test						1			
4.6	Sleeve strength (for sleeve items only)							1		
4.7	Resistance to Soldering Heat Test								5	
4.8	Composite temperature / humidity cyclic test									5

Test sample quality: 2 pcs min. / group